Low Frequency Timing-Safe™ Peak EMI reduction IC

General Features

- Low Frequency Clock distribution with Timing-Safe™ Peak EMI Reduction
- Input frequency range: 4MHz - 20MHz
- 2 different Spread Selection option
- Spread Spectrum can be turned ON/OFF
- External Input-Output Delay Control option
- Supply Voltage: 3.3V±0.3V
- Commercial and Industrial temperature range
- Packaging Information:
  ASM3P622S00B: 8 pin SOIC, and TSSOP
  ASM3P622S00E:16 pin SOIC, and TSSOP
- The First True Drop-in Solution

Functional Description

ASM3P622S00B/E is a versatile, 3.3V Zero-delay buffer designed to distribute low frequency Timing-Safe™ clocks with Peak EMI reduction. ASM3P622S00B is an eight-pin version, accepts one reference input and drives out one low-skew Timing-Safe™ clock. ASM3P622S00E accepts one reference input and drives out eight low-skew Timing-Safe™clocks.

ASM3P622S00B/E has an SS% that selects 2 different Deviation and associated Input-Output Skew (T_{SKEW}). Refer *Spread Spectrum Control and Input-Output Skew* table for details.

ASM3P622S00E has a CLKOUT for adjusting the Input-Output clock delay, depending upon the value of capacitor connected at this pin to GND.

ASM3P622S00B/E operates from a 3.3V supply and is available in two different packages, as shown in the ordering information table, over commercial and Industrial temperature range.

Application

ASM3P622S00B/E is targeted for use in Displays and memory interface systems.

General Block Diagram
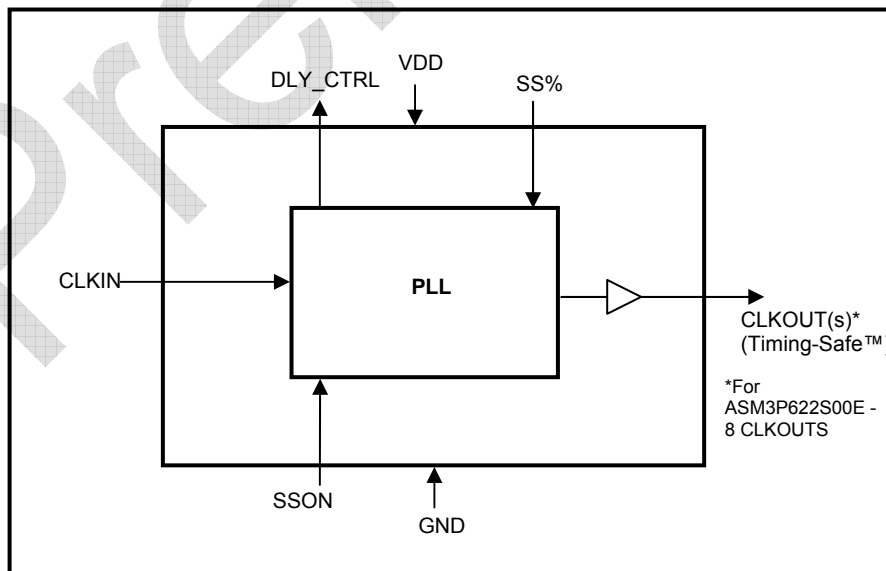
Spread Spectrum Frequency Generation

The clocks in digital systems are typically square waves with a 50% duty cycle and as frequencies increase the edge rates also get faster. Analysis shows that a square wave is composed of fundamental frequency and harmonics. The fundamental frequency and harmonics generate the energy peaks that become the source of EMI. Regulatory agencies test electronic equipment by measuring the amount of peak energy radiated from the equipment. In fact, the peak level allowed decreases as the frequency increases. The standard methods of reducing EMI are to use shielding, filtering, multi-layer PCBs etc. These methods are expensive. Spread spectrum clocking reduces the peak energy by reducing the Q factor of the clock. This is done by slowly modulating the clock frequency. The ASM3P622S00B/E uses the center modulation spread spectrum technique in which the modulated output frequency varies above and below the reference frequency with a specified modulation rate. With center modulation, the average frequency is the same as the unmodulated frequency and there is no performance degradation

Zero Delay and Skew Control

All outputs should be uniformly loaded to achieve Zero Delay between input and output. Since the CLKOUT pin is the internal feedback to the PLL, its relative loading can adjust the input-output delay.

For applications requiring zero input-output delay, all outputs, including CLKOUT, must be equally loaded. Even if CLKOUT is not used, it must have a capacitive load equal to that on other outputs, for obtaining zero-input-output delay.

Timing-Safe™ technology

Timing-Safe™ technology is the ability to modulate a clock source with Spread Spectrum technology and maintain synchronization with any associated data path.
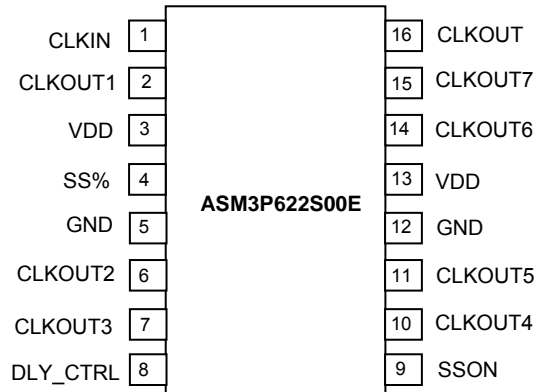
Pin Configuration for ASM3P622S00B
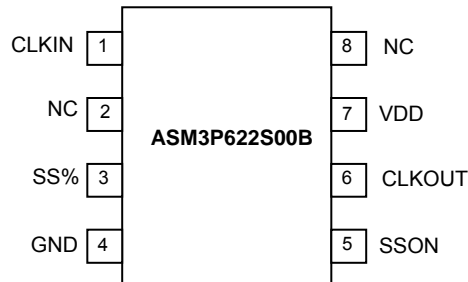
Pin Description for ASM3P622S00B

Pin #	Pin Name	Type	Description
1	CLKIN[1]	I	External reference Clock input , 5V tolerant input
2	NC		No Connect
3	SS%[3]	I	Spread Spectrum Selection. Has an internal pull up resistor
4	GND	P	Ground
5	SSON[3]	I	Spread Spectrum enable and disable option When SSON is HIGH, the spread spectrum is enabled and when LOW, it turns off the spread spectrum. Has an internal pull up resistor
6	CLKOUT[2]	O	Buffered clock output[4]
7	VDD	P	3.3V supply
8	NC		No Connect

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Pin Configuration for ASM3P622S00E

Pin Description for ASM3P622S00E

Pin #	Pin Name	Type	Description
1	CLKIN[1]	I	External reference Clock input, 5V tolerant input
2	CLKOUT1[2]	O	Buffered clock output[4]
3	V_{DD}	P	3.3V supply
4	SS%[3]	I	Spread Spectrum Selection. Refer *Spread Spectrum Control and Input-Output Skew* Table. Has an internal pull up resistor
5	GND	P	Ground
6	CLKOUT2[2]	O	Buffered clock output[4]
7	CLKOUT3[2]	O	Buffered clock output[4]
8	DLY_CTRL	O	External Input-Output Delay control.
9	SSON[3]	I	Spread Spectrum enable and disable option. When SSON is HIGH, the spread spectrum is enabled and when LOW, it turns off the spread spectrum. Has an internal pull up resistor
10	CLKOUT4[2]	O	Buffered clock output[4]
11	CLKOUT5[2]	O	Buffered clock output[4]
12	GND	P	Ground
13	V_{DD}	P	3.3V supply
14	CLKOUT6[2]	O	Buffered clock output[4]
15	CLKOUT7[2]	O	Buffered clock output[4]
16	CLKOUT[2]	O	Buffered clock output[4]

Notes: 1.Weak pull down
    2. Weak pull-down on all outputs
    3. Weak pull-up on these Inputs
    4. Buffered clock output is Timing-Safe™

Spread Spectrum Control and Input-Output Skew Table

Device	Input Frequency	SS %	Deviation	Input-Output Skew (±T_{SKEW})
ASM3P622S00B/E	12MHz	0	±0.25 %	0.0625
		1	±0.50 %	0.125

Note: T_{SKEW} is measured in units of the Clock Period

Absolute Maximum Ratings

Symbol	Parameter	Rating	Unit
VDD	Supply Voltage to Ground Potential	-0.5 to +4.6	V
VIN	DC Input Voltage (CLKIN)	-0.5 to +7	
T_{STG}	Storage temperature	-65 to +125	°C
T_s	Max. Soldering Temperature (10 sec)	260	°C
T_J	Junction Temperature	150	°C
T_{DV}	Static Discharge Voltage (As per JEDEC STD22- A114-B)	2	KV

Note: These are stress ratings only and are not implied for functional use. Exposure to absolute maximum ratings for prolonged periods of time may affect device reliability.

Operating Conditions

Parameter	Description	Min	Max	Unit
VDD	Supply Voltage	3.0	3.6	V
T_A	Operating Temperature (Ambient Temperature)	-40	+85	°C
C_L	Load Capacitance		30	pF
C_{IN}	Input Capacitance		7	pF

Electrical Characteristics

Parameter	Description	Test Conditions	Min	Typ	Max	Unit
V_{IL}	Input LOW Voltage[5]				0.8	V
V_{IH}	Input HIGH Voltage[5]		2.0			V
I_{IL}	Input LOW Current	V_{IN} = 0V			50	µA
I_{IH}	Input HIGH Current	V_{IN} = VDD			100	µA
V_{OL}	Output LOW Voltage[6]	I_{OL} = 8mA			0.4	V
V_{OH}	Output HIGH Voltage[6]	I_{OH} = -8mA	2.4			V
I_{DD}	Supply Current	Unloaded outputs			18	mA
Z_o	Output Impedance			23		Ω

Note: 5. CLKIN input has a threshold voltage of VDD/2
6. Parameter is guaranteed by design and characterization. Not 100% tested in production

rev 0.5

## Switching Characteristics for ASM3P622S00B/E

Parameter	Test Conditions		Min	Typ	Max	Unit
Input Frequency			4		20	MHz
Output Frequency	30pF load		4		20	MHz
Duty Cycle [6,7] = $(t_2 / t_1) * 100$	Measured at VDD/2		40	50	60	%
Output Rise Time [7, 8]	Measured between 0.8V and 2.0V				2.5	nS
Output Fall Time [7, 8]	Measured between 2.0V and 0.8V				2.5	nS
Output-to-output skew [7, 8]	All outputs equally loaded with SSOFF				250	pS
Delay, CLKIN Rising Edge to CLKOUT Rising Edge [8]	Measured at VDD /2 with SSOFF				±350	pS
Device-to-Device Skew [8]	Measured at VDD/2 on the CLKOUT pins of the device				700	pS
Cycle-to-Cycle Jitter [7, 8]	Loaded outputs	< 8MHz			±1.6	nS
		> 8MHz			±200	pS
PLL Lock Time [8]	Stable power supply, valid clock presented on CLKIN pin				1.0	mS

Note: 7. All parameters specified with 30pF loaded outputs.
   8. Parameter is guaranteed by design and characterization. Not 100% tested in production
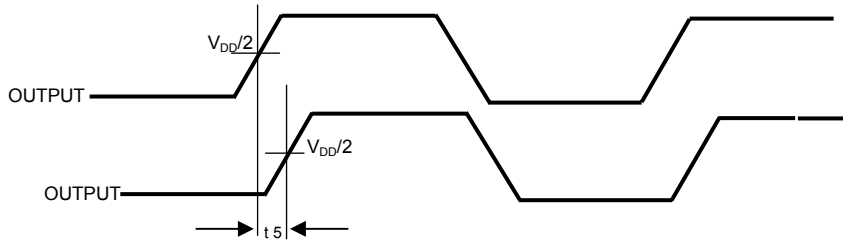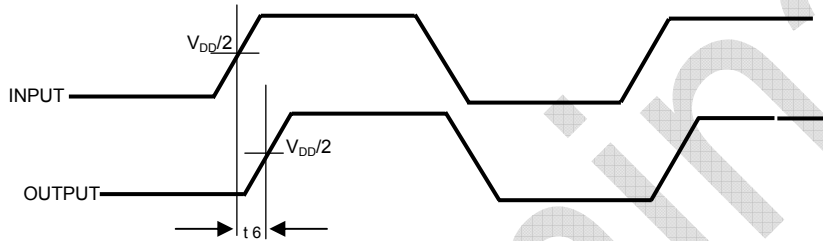
Switching Waveforms

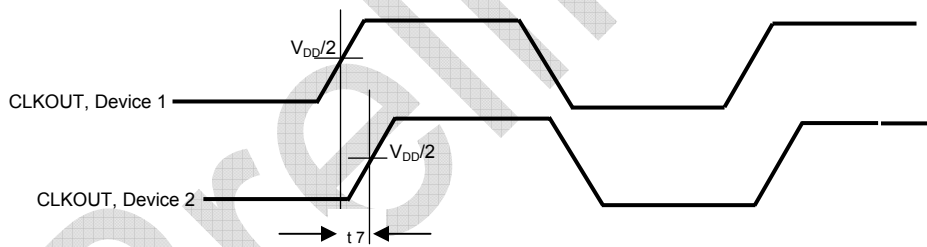### Duty Cycle Timing
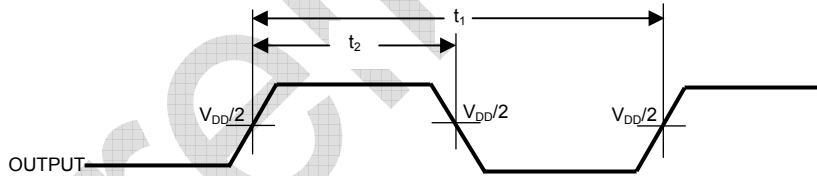
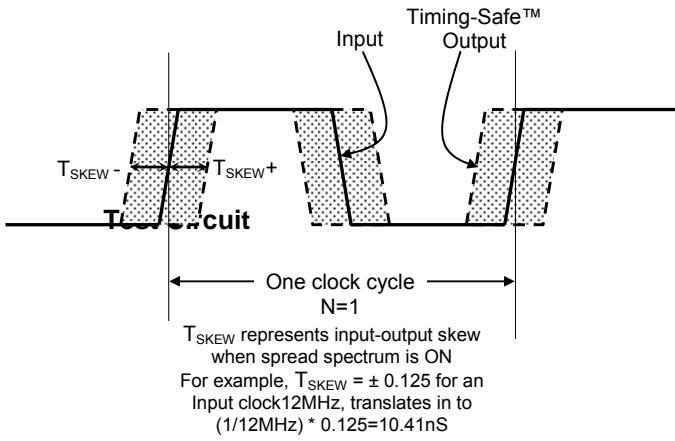### All Outputs Rise/Fall Time
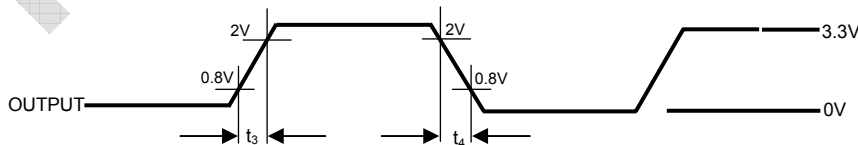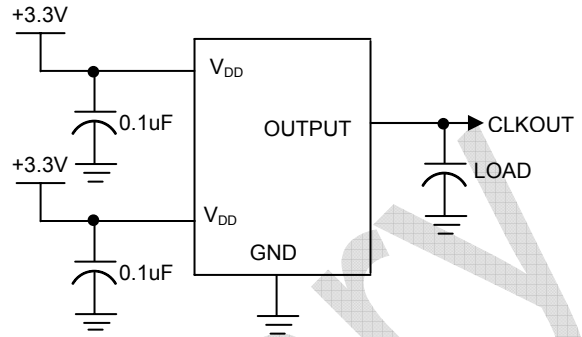
Output - Output Skew

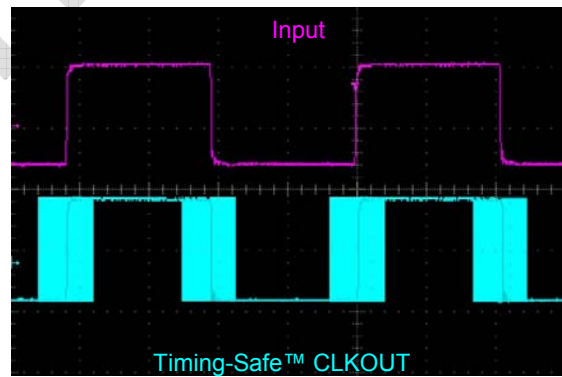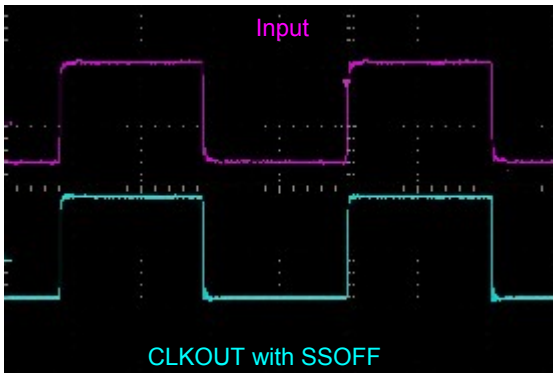## Input - Output Propagation Delay
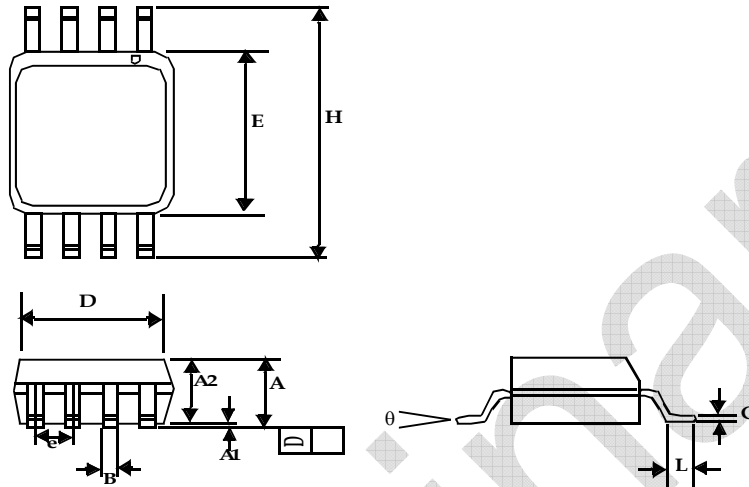

Device - Device Skew

Input-Output Skew

T_{SKEW} - T_{SKEW}+

One clock cycle
N=1

T_{SKEW} represents input-output skew
when spread spectrum is ON
For example, $T_{SKEW} = \pm 0.125$ for an
Input clock12MHz, translates in to
(1/12MHz) * 0.125=10.41nS

Test Circuit

A Typical example of Timing-Safe™ waveform

CLKOUT with SSOFF

Timing-Safe™ CLKOUT

Package Information

8-lead (150-mil) SOIC Package

Symbol	Dimensions			
	Inches		**Millimeters**	
	Min	**Max**	**Min**	**Max**
A1	0.004	0.010	0.10	0.25
A	0.053	0.069	1.35	1.75
A2	0.049	0.059	1.25	1.50
B	0.012	0.020	0.31	0.51
C	0.007	0.010	0.18	0.25
D	0.193 BSC		4.90 BSC	
E	0.154 BSC		3.91 BSC	
e	0.050 BSC		1.27 BSC	
H	0.236 BSC		6.00 BSC	
L	0.016	0.050	0.41	1.27
θ	0°	8°	0°	8°

8-lead TSSOP (4.40-MM Body)
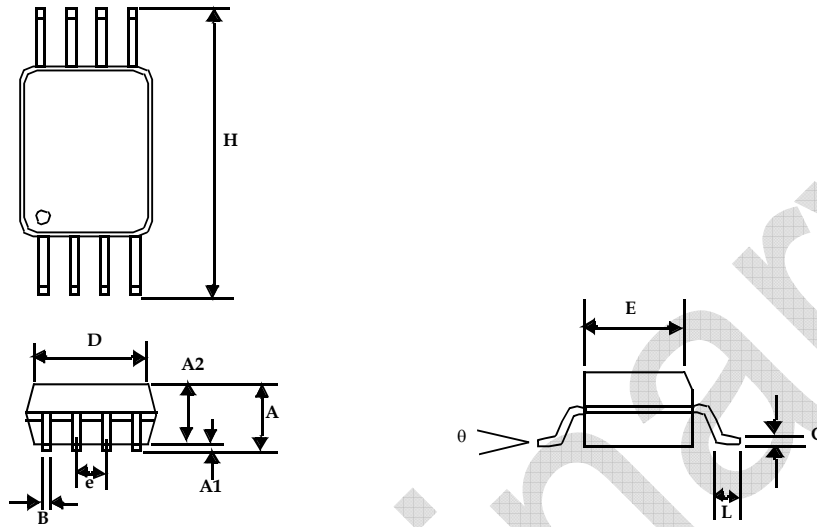
Symbol	Dimensions			
	Inches		Millimeters	
	Min	Max	Min	Max
A		0.043		1.10
A1	0.002	0.006	0.05	0.15
A2	0.033	0.037	0.85	0.95
B	0.008	0.012	0.19	0.30
c	0.004	0.008	0.09	0.20
D	0.114	0.122	2.90	3.10
E	0.169	0.177	4.30	4.50
e	0.026 BSC		0.65 BSC	
H	0.252 BSC		6.40 BSC	
L	0.020	0.028	0.50	0.70
θ	0°	8°	0°	8°

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16-lead (150 Mil) Molded SOIC Package
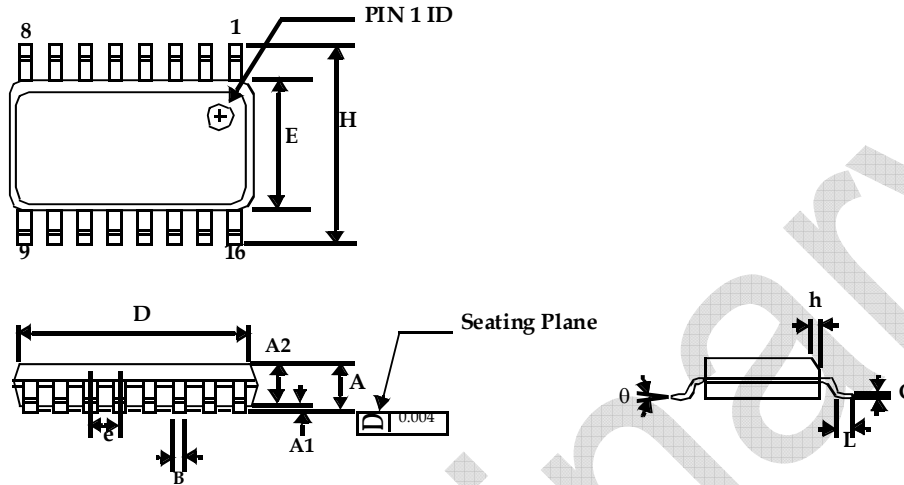
Symbol	Dimensions			
	Inches		Millimeters	
	Min	Max	Min	Max
A	0.053	0.069	1.35	1.75
A1	0.004	0.010	0.10	0.25
A2	0.049	0.059	1.25	1.50
B	0.013	0.022	0.33	0.53
C	0.008	0.012	0.19	0.27
D	0.386	0.394	9.80	10.01
E	0.150	0.157	3.80	4.00
e	0.050 BSC		1.27 BSC	
H	0.228	0.244	5.80	6.20
h	0.010	0.016	0.25	0.41
L	0.016	0.035	0.40	0.89
θ	0°	8°	0°	8°

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16-lead TSSOP (4.40-MM Body)
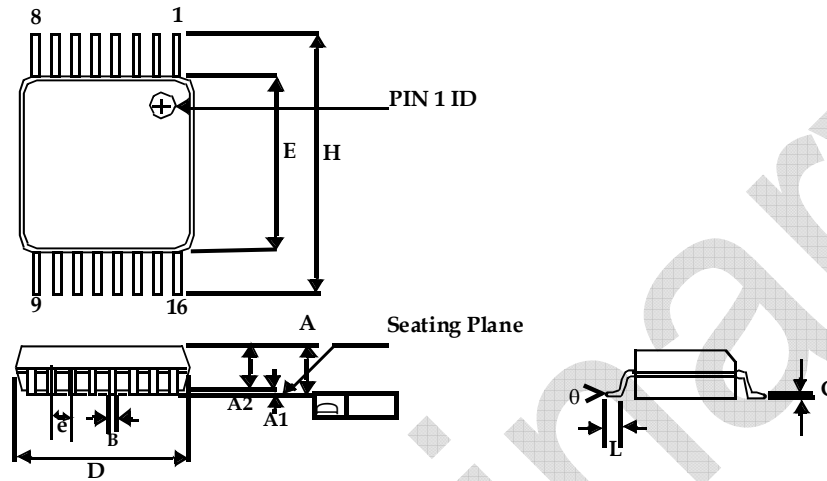
Symbol	Dimensions			
	Inches		Millimeters	
	Min	**Max**	**Min**	**Max**
A		0.043		1.20
A1	0.002	0.006	0.05	0.15
A2	0.031	0.041	0.80	1.05
B	0.007	0.012	0.19	0.30
C	0.004	0.008	0.09	0.20
D	0.193	0.201	4.90	5.10
E	0.169	0.177	4.30	4.50
e	0.026 BSC		0.65 BSC	
H	0.252 BSC		6.40 BSC	
L	0.020	0.030	0.50	0.75
θ	0°	8°	0°	8°

Ordering Code

Ordering Code	Marking	Package Type	Temperature
ASM3P622S00BF-08-ST	3P622S00BF	8-pin 150-mil SOIC-TUBE, Pb Free	Commercial
ASM3I622S00BF-08-ST	3I622S00BF	8-pin 150-mil SOIC-TUBE, Pb Free	Industrial
ASM3P622S00BF-08-SR	3P622S00BF	8-pin 150-mil SOIC-TAPE & REEL, Pb Free	Commercial
ASM3I622S00BF-08-SR	3I622S00BF	8-pin 150-mil SOIC-TAPE & REEL, Pb Free	Industrial
ASM3P622S00BF-08-TT	3P622S00BF	8-pin 4.4-mm TSSOP - TUBE, Pb Free	Commercial
ASM3I622S00BF-08-TT	3I622S00BF	8-pin 4.4-mm TSSOP - TUBE, Pb Free	Industrial
ASM3P622S00BF-08-TR	3P622S00BF	8-pin 4.4-mm TSSOP - TAPE & REEL, Pb Free	Commercial
ASM3I622S00BF-08-TR	3I622S00BF	8-pin 4.4-mm TSSOP - TAPE & REEL, Pb Free	Industrial
ASM3P622S00EF-16-ST	3P622S00EF	16-pin 150-mil SOIC-TUBE, Pb Free	Commercial
ASM3I622S00EF-16-ST	3I622S00EF	16-pin 150-mil SOIC-TUBE, Pb Free	Industrial
ASM3P622S00EF-16-SR	3P622S00EF	16-pin 150-mil SOIC-TAPE & REEL, Pb Free	Commercial
ASM3I622S00EF-16-SR	3I622S00EF	16-pin 150-mil SOIC-TAPE & REEL, Pb Free	Industrial
ASM3P622S00EF-16-TT	3P622S00EF	16-pin 4.4-mm TSSOP - TUBE, Pb Free	Commercial
ASM3I622S00EF-16-TT	3I622S00EF	16-pin 4.4-mm TSSOP - TUBE, Pb Free	Industrial
ASM3P622S00EF-16-TR	3P622S00EF	16-pin 4.4-mm TSSOP - TAPE & REEL, Pb Free	Commercial
ASM3I622S00EF-16-TR	3I622S00EF	16-pin 4.4-mm TSSOP - TAPE & REEL, Pb Free	Industrial
ASM3P622S00BG-08-ST	3P622S00BG	8-pin 150-mil SOIC-TUBE, Pb Free	Commercial
ASM3I622S00BG-08-ST	3I622S00BG	8-pin 150-mil SOIC-TUBE, Pb Free	Industrial
ASM3P622S00BG-08-SR	3P622S00BG	8-pin 150-mil SOIC-TAPE & REEL, Pb Free	Commercial
ASM3I622S00BG-08-SR	3I622S00BG	8-pin 150-mil SOIC-TAPE & REEL, Pb Free	Industrial
ASM3P622S00BG-08-TT	3P622S00BG	8-pin 4.4-mm TSSOP - TUBE, Pb Free	Commercial
ASM3I622S00BG-08-TT	3I622S00BG	8-pin 4.4-mm TSSOP - TUBE, Pb Free	Industrial
ASM3P622S00BG-08-TR	3P622S00BG	8-pin 4.4-mm TSSOP - TAPE & REEL, Pb Free	Commercial
ASM3I622S00BG-08-TR	3I622S00BG	8-pin 4.4-mm TSSOP - TAPE & REEL, Pb Free	Industrial
ASM3P622S00EG-16-ST	3P622S00EG	16-pin 150-mil SOIC-TUBE, Green	Commercial
ASM3I622S00EG-16-ST	3I622S00EG	16-pin 150-mil SOIC-TUBE, Green	Industrial
ASM3P622S00EG-16-SR	3P622S00EG	16-pin 150-mil SOIC-TAPE & REEL, Green	Commercial
ASM3I622S00EG-16-SR	3I622S00EG	16-pin 150-mil SOIC-TAPE & REEL, Green	Industrial
ASM3P622S00EG-16-TT	3P622S00EG	16-pin 4.4-mm TSSOP - TUBE, Green	Commercial
ASM3I622S00EG-16-TT	3I622S00EG	16-pin 4.4-mm TSSOP - TUBE, Green	Industrial
ASM3P622S00EG-16-TR	3P622S00EG	16-pin 4.4-mm TSSOP - TAPE & REEL, Green	Commercial
ASM3I622S00EG-16-TR	3I622S00EG	16-pin 4.4-mm TSSOP - TAPE & REEL, Green	Industrial

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Device Ordering Information

A S M 3 P 6 2 2 S 0 0 B G - 0 8 - T R

R = Tape & Reel, T = Tube or Tray	

O = TSOT23	U = MSOP	J=TSOT26
S = SOIC	E = TQFP	C=TDFN (2X2) COL
T = TSSOP	L = LQFP	
A = SSOP	U = MSOP	
V = TVSOP	P = PDIP	
B = BGA	D = QSOP	
Q = QFN	X = SC-70	

DEVICE PIN COUNT

F = LEAD FREE AND RoHS COMPLIANT PART
G = GREEN PACKAGE, LEAD FREE, and RoHS

PART NUMBER

X= Automotive	I= Industrial	P or n/c = Commercial
(-40C to +125C)	(-40C to +85C)	(0C to +70C)

1 = Clock Generator	6 = Power Management
2 = Non PLL based	7 = Power Management
3 = EMI Reduction	8 = Power Management
4 = DDR support products	9 = Hi Performance
5 = STD Zero Delay Buffer	0 = Reserved

PulseCore Semiconductor Mixed Signal Product

Licensed under US patent #5,488,627, #6,646,463 and #5,631,920.

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www.pulsecoresemi.com

Note: This product utilizes US Patent # 6,646,463 Impedance Emulator Patent issued to PulseCore Semiconductor, dated 11-11-2003
Many PulseCore Semiconductor products are protected by issued patents or by applications for patent

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